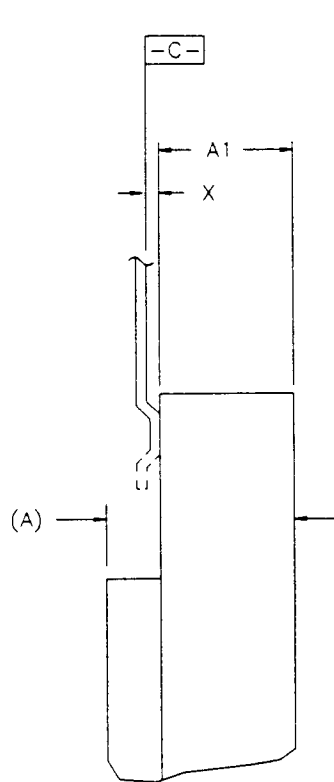
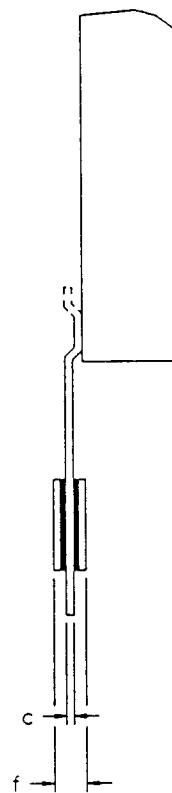


National Semiconductor has stated that U.S. Patent No. 4,796,080 may relate to a certain implementation of this package outline. The sponsor has not agreed with this statement.

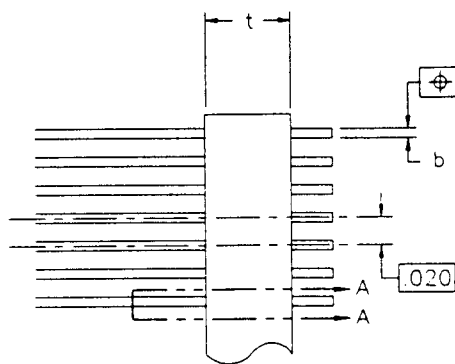
<p>JEDEC Solid State Product Outline</p>	<p>TOP BRAZED CERAMIC LEADED CHIP CARRIER (.020 INCH LEAD PITCH) WITH PLASTIC NON-CONDUCTIVE TIE BAR</p>	<p>ISSUE A</p>	<p>DATE Sept. 1992</p>	<p>M0-129</p>	<p>SHEET 1/5</p>
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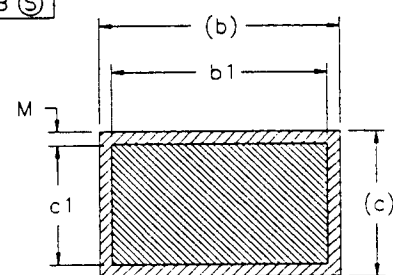
DETAIL A



DETAIL B

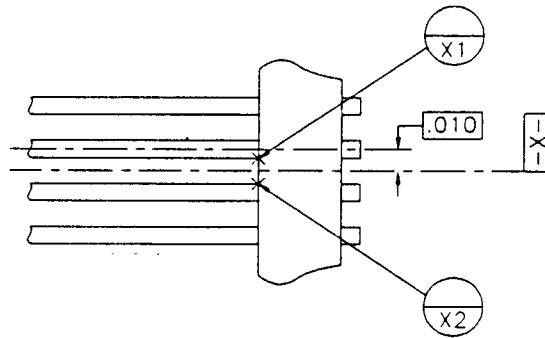


DETAIL C



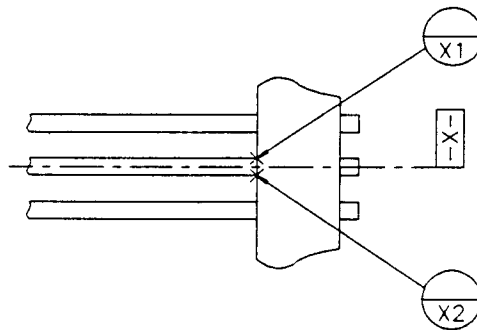
SECTION A-A

<p>JEDEC Solid State Product Outline</p>	<p>TOP BRAZED CERAMIC LEADED CHIP CARRIER (.020 INCH LEAD PITCH) WITH PLASTIC NON-CONDUCTIVE TIE BAR</p>	<p>ISSUE A</p>	<p>DATE Sept. 1992</p>	<p>MO-129</p>	<p>SHEET 2/5</p>
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X = -A- , -B- OR -D-

EVEN LEAD SIDES $\triangle 7$



X = -A- , -B- OR -D-

ODD LEAD SIDES $\triangle 7$

DETAIL "D"

JEDEC
Solid State Product
Outline

TOP BRAZED
CERAMIC LEADED CHIP CARRIER
(.020 INCH LEAD PITCH)
WITH PLASTIC NON-CONDUCTIVE
TIE BAR

ISSUE

A

DATE

Sept.
1992

MO-129

SHEET

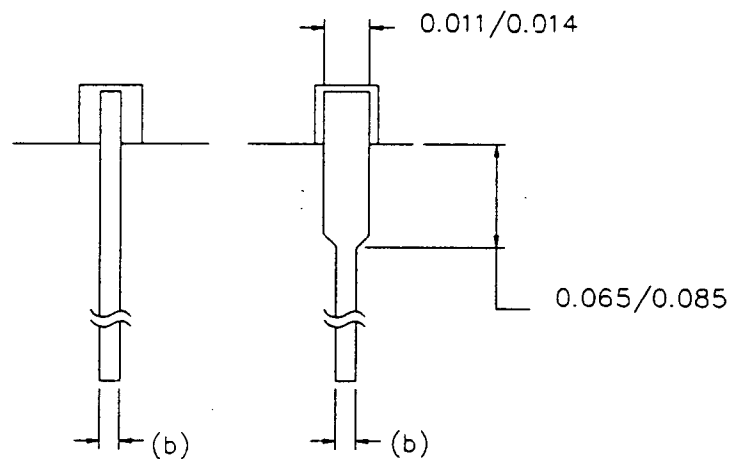
3/5

SYMBOL	VARIATIONS							
	AA			NOTE	AB			NOTE
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.	
A	—	—	0.172		—	—	0.172	
A1	0.082	0.092	0.100		0.092	0.096	0.100	
b	0.007	0.008	0.010		0.007	0.008	0.010	
b1	0.006	0.007	0.009	6	0.006	0.007	0.009	6
c	0.004	0.005	0.006		0.004	0.005	0.006	
c1	0.003	0.004	0.005	6	0.003	0.004	0.005	6
D	1.453	1.460	1.467		1.840	1.850	1.860	
D2	2.180	2.190	2.200		2.660	2.670	2.680	
D3	2.200	2.210	2.220		2.715	2.725	2.735	
D4	1.280	1.290	1.300		1.730	1.740	1.750	
E	1.453	1.460	1.467		1.840	1.850	1.860	
E2	2.180	2.190	2.200		2.660	2.670	2.680	
E3	2.200	2.210	2.220		2.715	2.725	2.735	
E4	1.280	1.290	1.300		1.730	1.740	1.750	
f	0.015	0.035	0.045		0.015	0.035	0.045	
X	0.002	0.008	0.014		0.002	0.008	0.014	
L1	0.235	—	—		0.280	—	—	
M	—	—	0.0005	6	—	—	0.0005	6
t	0.065	—	0.130		0.065	—	0.130	
N		256		3		340		3
NOTE 1.7								
REF ITEM 10-298								
ISSUE A								

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LEAD OPTIONS $\triangle 4$

OPTION A OPTION B



NOTES:

1. All dimensions are in inches.

$\triangle 2$ Plastic tie bar corners with or without metal leadframe corners may be included in the "as is" shipped package.

3. Dimension N: Number of leads. For drawing clarity, not all leads are shown. Actual packages have a continuous array of leads.

$\triangle 4$ Straight or step option.

5 Plastic tie bar will not overhang lead tips.

$\triangle 6$ Dimensions b1 and c1 apply to base metal only.
Dimension M applies to plating thickness.

$\triangle 7$ Datum $\boxed{A-D}$ and $\boxed{-B-}$ to be determined by datum points where leads contact the tie bar.

8. Dimensioning and tolerancing per ANSI Y14.5M-1982.

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